



## 40V N&P-Channel Trench Power MOSFET

### General Description

The SJH40NP330 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

### Features

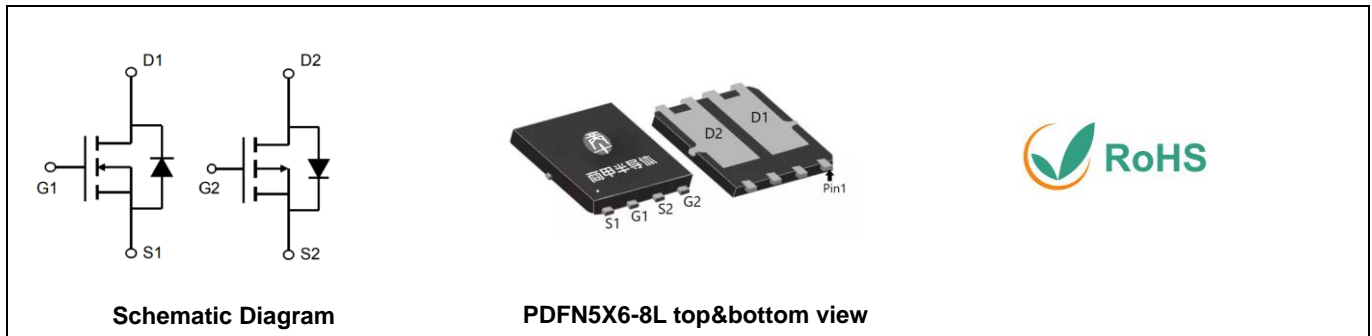
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### Key Performance Parametes

Parameter	Value	Value	Unit
$V_{DS}$	40	-40	V
$R_{DS(ON\_TYP)}$	12.5	11.8	m $\Omega$
$I_D$	30	-44	A
$Q_G$	24.5	60	nC



### Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJH40NP330	SJH40NP330	PDFN5X6-8L	Tape	\	\	5000 Pcs

**Table 1. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	N Limit	P Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0V$ )	40	-40	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0V$ )	$\pm 20$	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	30	-44	A
	Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	19	-28	A
$I_{DM}(\text{pulse})$	Drain Current-Continuous@ Current-Pulsed (Note 1)	120	-176	A
$P_D$	Maximum Power Dissipation( $T_C=25^\circ\text{C}$ )	29	50	W
	Maximum Power Dissipation( $T_C=100^\circ\text{C}$ )	11.4	20	W
$E_{AS}$	Avalanche energy (Note 2)	90	272	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150		$^\circ\text{C}$

**Table 2. Thermal Characteristic**

Symbol	Parameter	N Limit	P Limit	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to- Case	4.37	2.48	$^\circ\text{C/W}$



## 40V N&P-Channel Trench Power MOSFET

**Table 3. N-Channel Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃			1	μA
		V <sub>DS</sub> =40V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1		2.5	V
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =15A		27.2		S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A T <sub>J</sub> =25℃		12.5	16.3	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A T <sub>J</sub> =25℃		15.6	20.7	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1.0MHz		1314		pF
C <sub>oss</sub>	Output Capacitance			95.4		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			78.5		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		1.8		Ω
Switching Parameters						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, R <sub>L</sub> =1Ω, R <sub>GEN</sub> =3Ω		12.6		nS
t <sub>r</sub>	Turn-on Rise Time			3.6		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			30.8		nS
t <sub>f</sub>	Turn-Off Fall Time			3.2		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, I <sub>D</sub> =20A		24.5		nC
Q <sub>gs</sub>	Gate-Source Charge			3.7		nC
Q <sub>gd</sub>	Gate-Drain Charge			6.2		nC
Source-Drain Diode Characteristics						
I <sub>SD</sub>	Source-Drain Current (Body Diode)				30	A
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =3A			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=100A/μs		17.5		ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =20A, dI/dt=100A/μs		10.9		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=30V, V_G=10V, R_g=25\Omega, L=0.5mH$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



## 40V N&P-Channel Trench Power MOSFET

### N-Channel Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

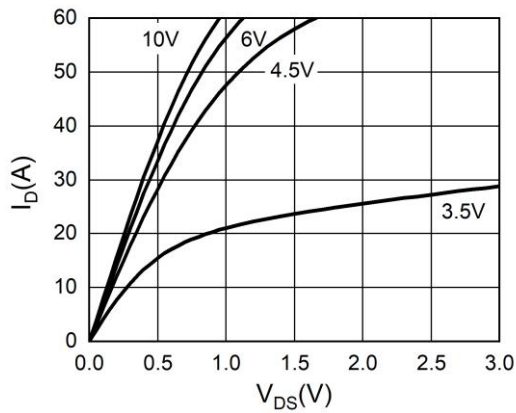


Figure 2. Transfer Characteristics

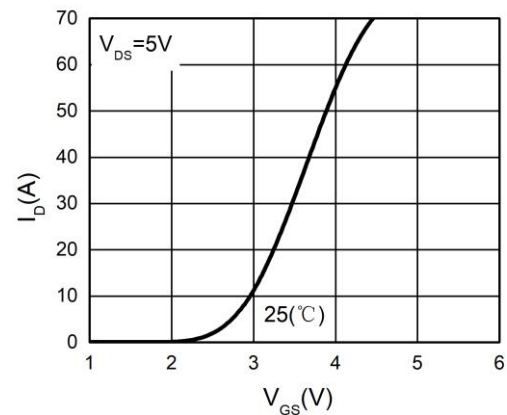


Figure 3. Power Dissipation

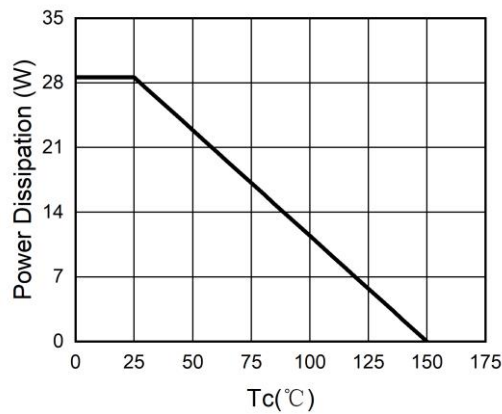


Figure 4. Drain Current

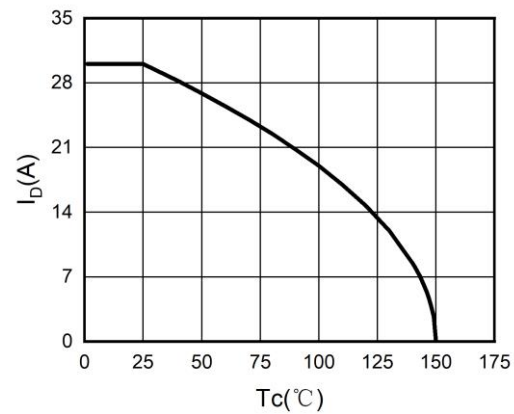


Figure 5.  $BV_{DSS}$  vs Junction Temperature

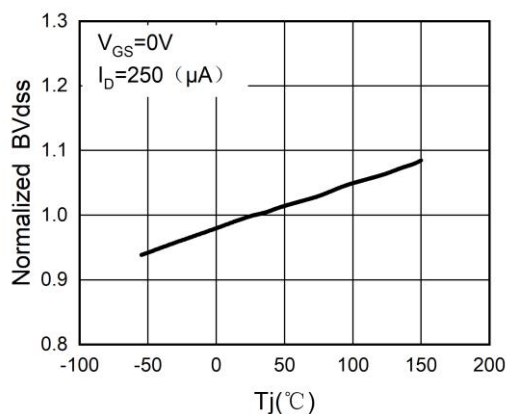
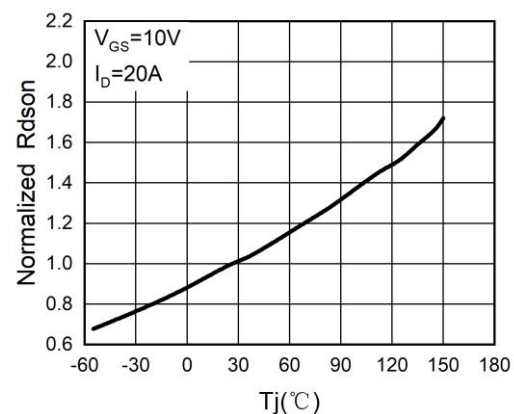


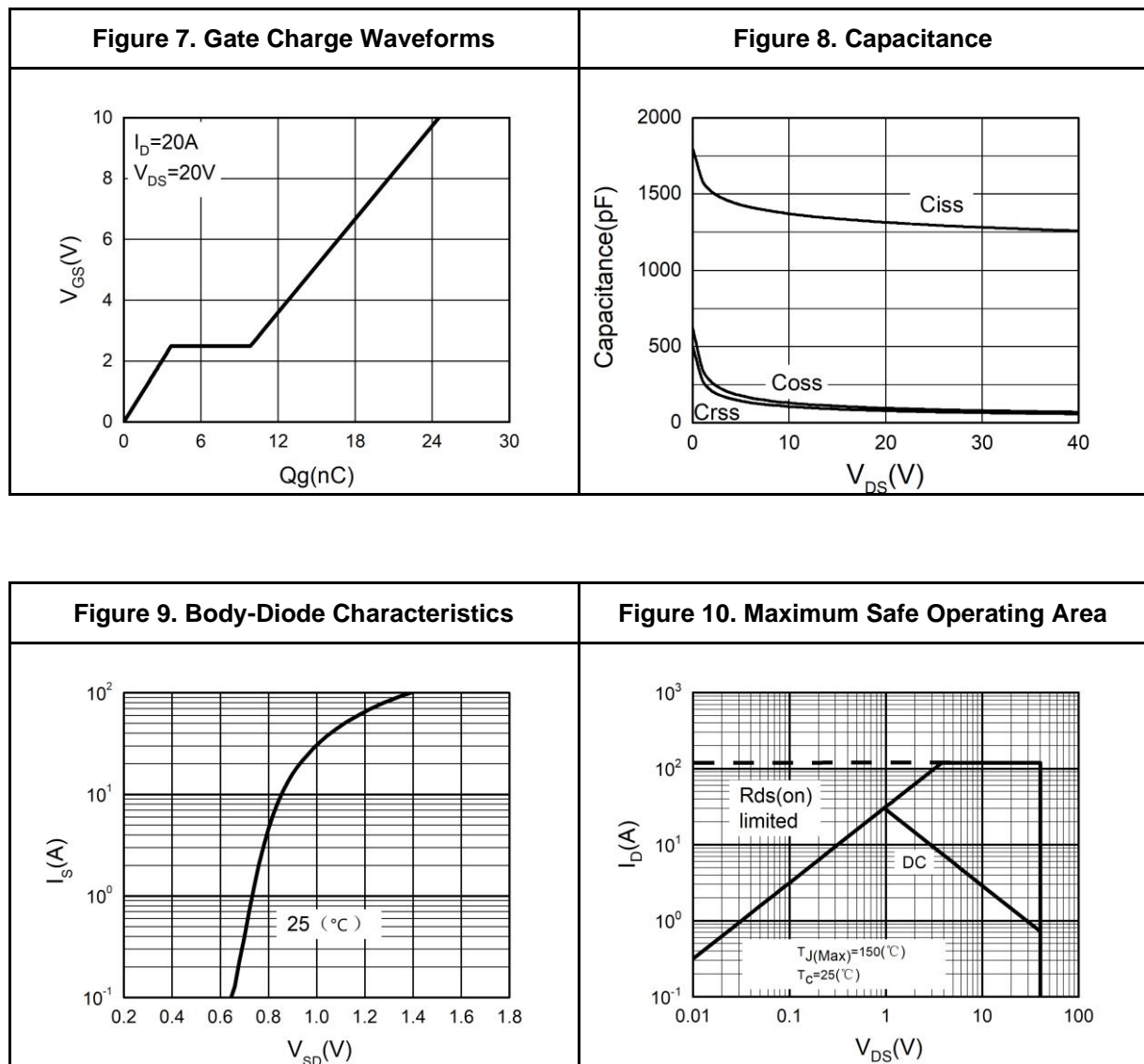
Figure 6.  $R_{DS(ON)}$  vs Junction Temperature





## 40V N&P-Channel Trench Power MOSFET

### N-Channel Typical Electrical And Thermal Characteristics (Curves)





## 40V N&P-Channel Trench Power MOSFET

**Table 4. P-Channel Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃			-1	μA
		V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			-100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1		-2.5	V
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-15A		26.3		S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A T <sub>J</sub> =25℃		11.8	15.3	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A T <sub>J</sub> =25℃		15.6	20.7	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, f=1.0MHz		3241		pF
C <sub>oss</sub>	Output Capacitance			228		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			205		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		4.5		Ω
Switching Parameters						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, R <sub>L</sub> =1Ω, R <sub>GEN</sub> =3Ω		18		nS
t <sub>r</sub>	Turn-on Rise Time			4.8		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			88.8		nS
t <sub>f</sub>	Turn-Off Fall Time			26.4		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, I <sub>D</sub> =-20A		60		nC
Q <sub>gs</sub>	Gate-Source Charge			8.6		nC
Q <sub>gd</sub>	Gate-Drain Charge			13.9		nC
Source-Drain Diode Characteristics						
I <sub>SD</sub>	Source-Drain Current (Body Diode)				-44	A
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =-20A			-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-20A, dI/dt=-100A/μs		17.3		ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =-20A, dI/dt=-100A/μs		9.5		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=-40V, V_G=-10V, R_g=25\Omega, L=0.5\text{mH}$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



## 40V N&P-Channel Trench Power MOSFET

### P-Channel Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

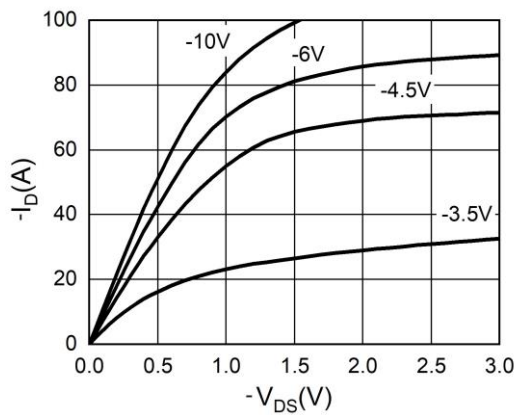


Figure 2. Transfer Characteristics

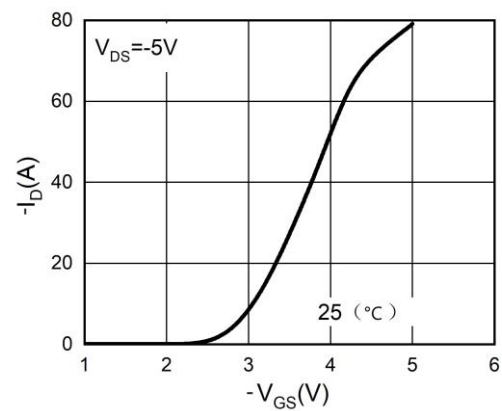


Figure 3. Power Dissipation

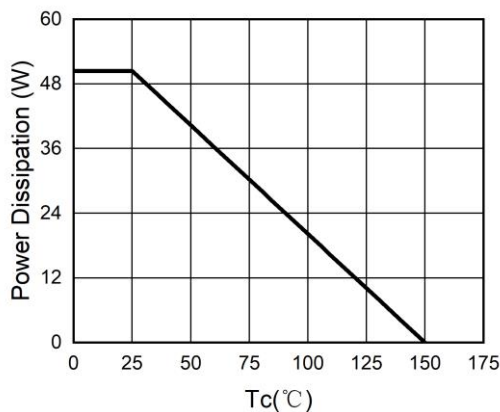


Figure 4. Drain Current

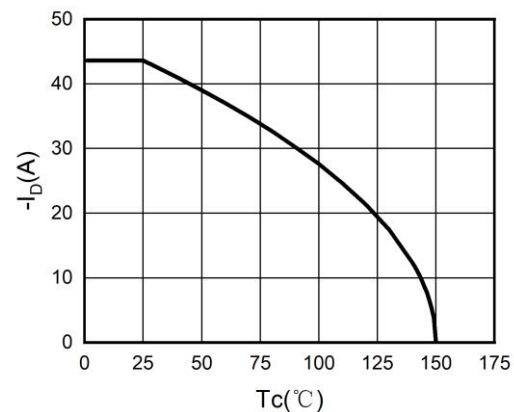


Figure 5.  $BV_{DSS}$  vs Junction Temperature

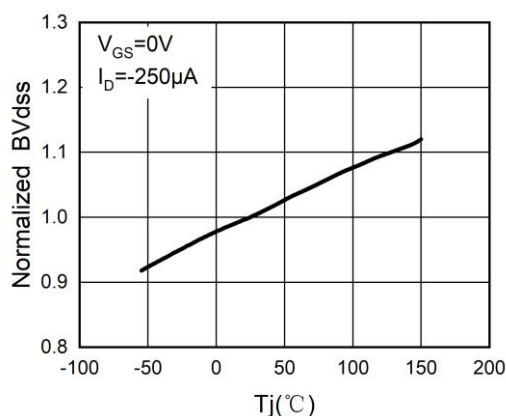
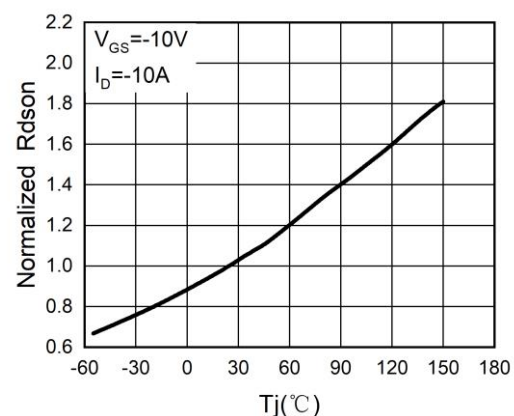


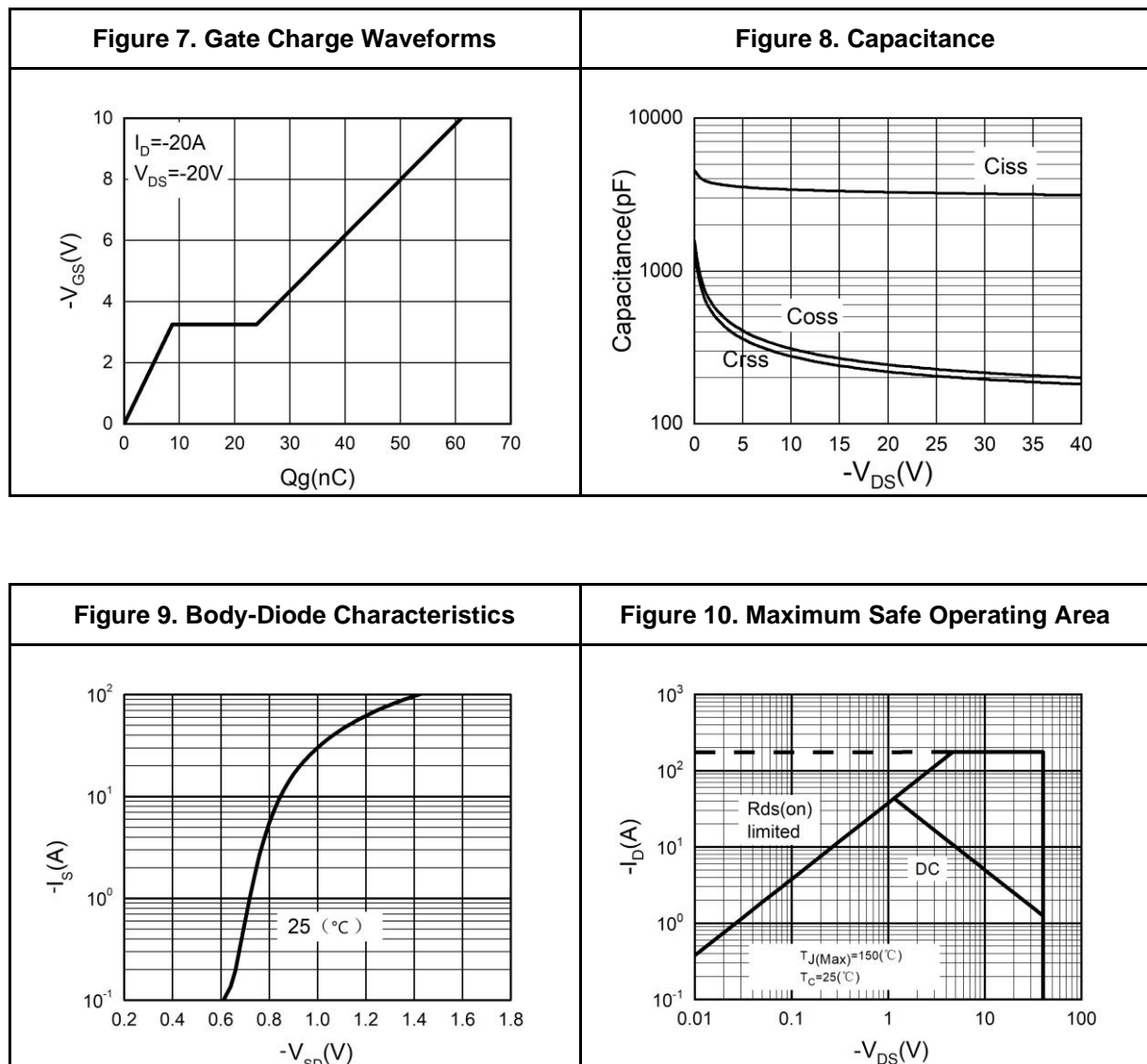
Figure 6.  $R_{DS(ON)}$  vs Junction Temperature





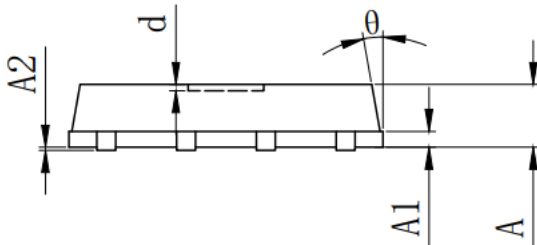
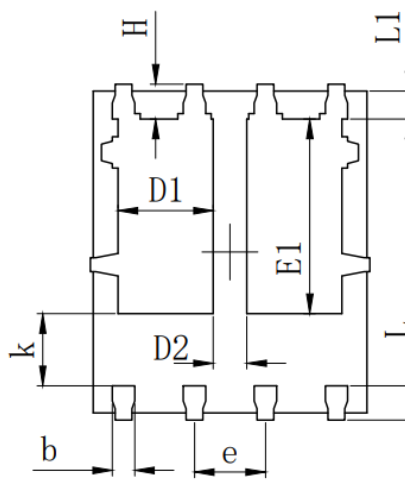
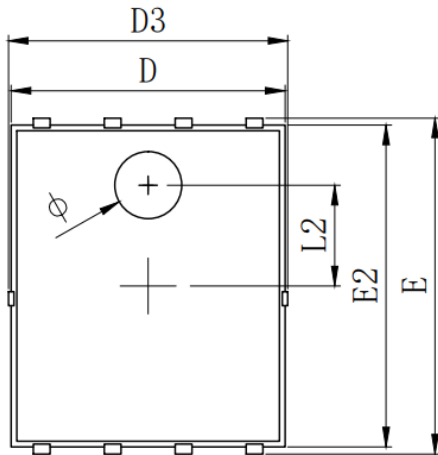
## 40V N&P-Channel Trench Power MOSFET

### P-Channel Typical Electrical And Thermal Characteristics (Curves)





PDFN5X6-8L Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254 REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	1.605	1.705	1.805
D2	0.500	0.600	0.700
D3	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
φ	1.100	1.200	1.300
d			0.100





## 40V N&P-Channel Trench Power MOSFET

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### Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

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